

Title (en)  
UNIVERSAL ENERGY CONDITIONING INTERPOSER WITH CIRCUIT ARCHITECTURE

Title (de)  
UNIVERSELLES ENERGIEANPASSUNGSZWISCHENSTÜCK MIT SCHALTUNGSARCHITEKTUR

Title (fr)  
DISPOSITIF D'INTERPOSITION UNIVERSEL DESTINE AU CONDITIONNEMENT D'ENERGIE ET MUNI D'UNE ARCHITECTURE DE CIRCUIT

Publication  
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Application  
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- US 46021899 A 19991213
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- US 20032700 P 20000428
- US 20386300 P 20000512
- US 57960600 A 20000526
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Abstract (en)  
[origin: WO0110000A1] The present invention relates to an interposer substrate (310) for interconnecting between active electronic componentry such as but not limited to a single or multiple integrated circuit (4100) chips in either a single or a combination, and elements that could comprise of a mounting substrate, substrate module, a printed circuit board, integrated circuit chips or other substrates containing conductive energy pathways that service an energy utilizing load and leading to and from an energy source.

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